

P- Channel 40-V (D-S) MOSFET

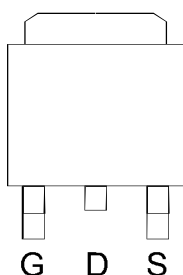
GENERAL DESCRIPTION

The ME12P04 is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching, and low in-line power loss are needed in a very small outline surface mount package.

PIN CONFIGURATION

(TO-252)

Top View

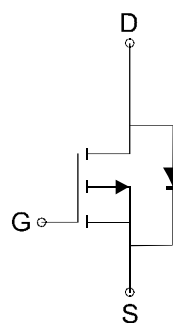


FEATURES

- $R_{DS(ON)} \leq 45m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} \leq 80m\Omega @ V_{GS} = -4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- LCD Display inverter



P-Channel MOSFET

Ordering Information: ME12P04 (Pb-free)

ME12P04-G (Green product)

Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)

Parameter		Symbol	Maximum		Unit
Drain-Source Voltage		V _{DSS}	-40		V
Gate-Source Voltage		V _{GSS}	±25		V
Continuous Drain Current(T _j =150°C)*	T _C =25°C	I _D	-18.6		A
	T _C =70°C		-15		
Pulsed Drain Current		I _{DM}	-75		A
Maximum Power Dissipation	T _C =25°C	P _D	25		W
	T _C =70°C		16		
Operating Junction Temperature		T _J	-55 to 150		°C
Thermal Resistance-Junction to Ambient*		R _{θJA}	T ≤ 10 sec	20	°C/W
			Steady State	42	
Thermal Resistance-Junction to Case*		R _{θJC}	5		°C/W

*The device mounted on 1in² FR4 board with 2 oz copper

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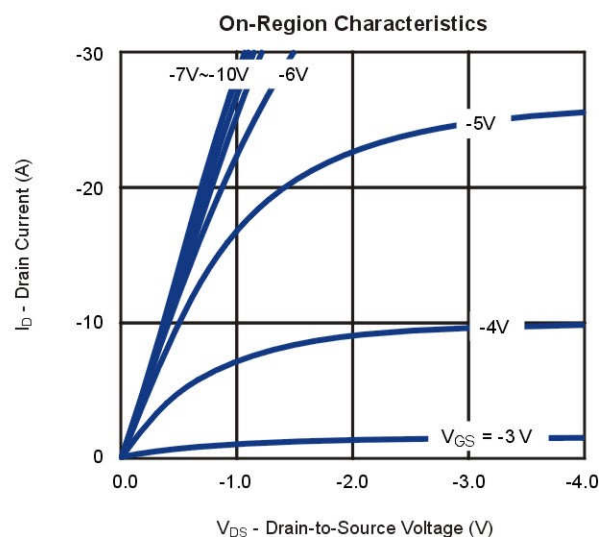
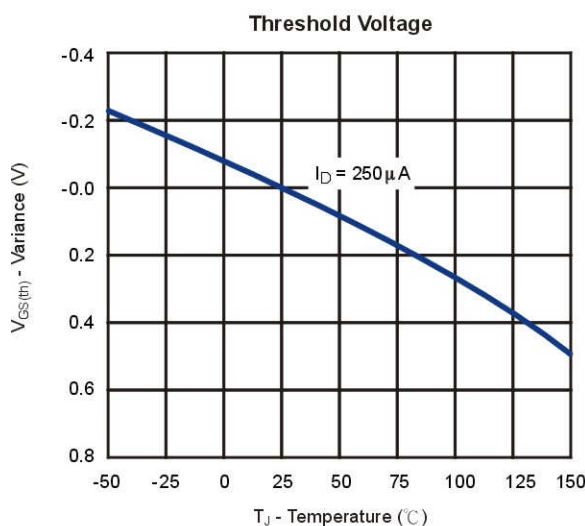
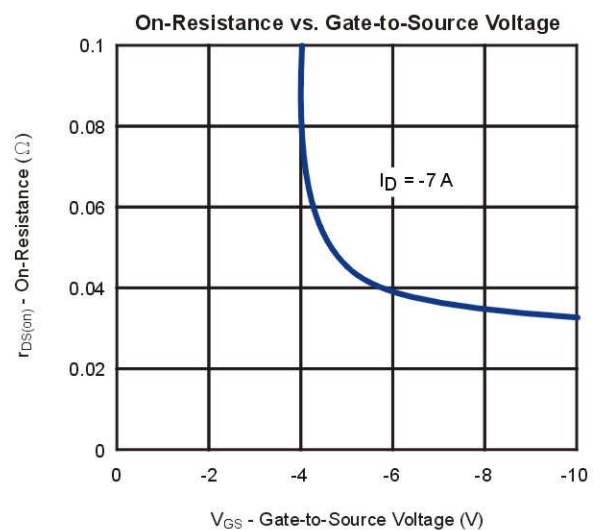
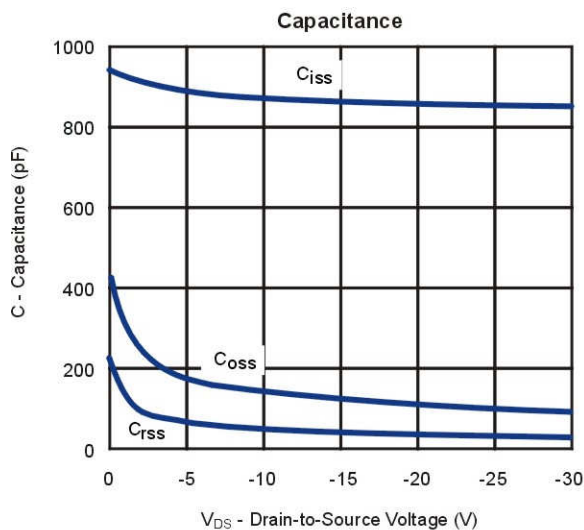
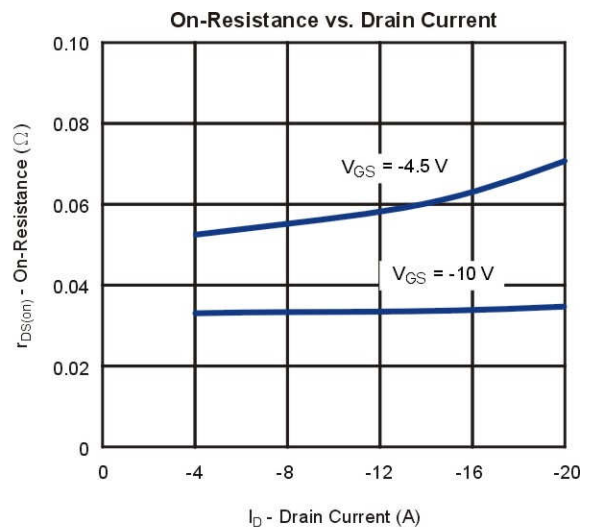
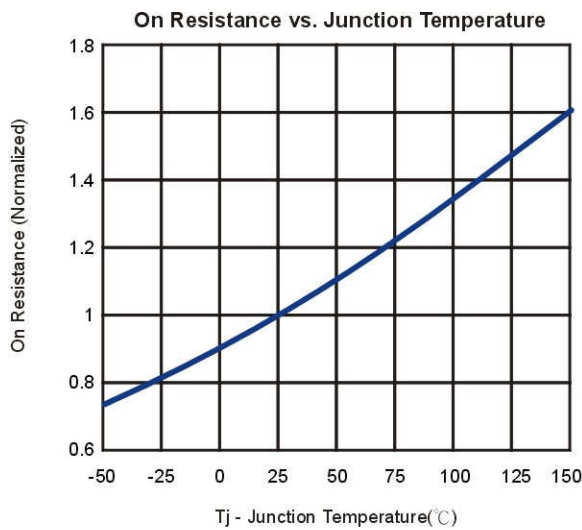
Electrical Characteristics (TA=25°C Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
V(BR)DSS	Drain-Source Breakdown Voltage	VGS=0V, ID=-250 μ A	-40			V
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=-250 μ A	-1	-1.9	-3	V
IGSS	Gate Leakage Current	VDS=0V, VGS=±25V			±100	nA
IDSS	Zero Gate Voltage Drain Current	VDS=-40V, VGS=0V			1	μ A
		VDS=-40V, VGS=0V, TJ=55°C			10	
RDS(ON)	Drain-Source On-State Resistance ^a	VGS=-10V, ID= -12A		35	45	m Ω
		VGS=-4.5V, ID= -6A		57	80	
VSD	Diode Forward Voltage	IS=-1.7A, VGS=0V		0.78	1.2	V
DYNAMIC						
Qg	Total Gate Charge	VDS=-20V, VGS=-4.5V, ID=-12A		10		nC
Qgs	Gate-Source Charge			4.3		
Qgd	Gate-Drain Charge			4.5		
Rg	Gate Resistance	VGS=0V, VDS=0V, f=1MHz		6		Ω
Ciss	Input capacitance	VDS=-20V, VGS=0V, F=1MHz		860		pF
Coss	Output Capacitance			120		
Crss	Reverse Transfer Capacitance			35		
td(on)	Turn-On Delay Time	VDD=-15V, RL =15 Ω ID=-1A, VGEN=-10V, RG=6 Ω		30		ns
tr	Turn-On Rise Time			8.5		
td(off)	Turn-Off Delay Time			70		
tf	Turn-Off Fall Time			7		

Notes:a. Pulse test; pulse width \leq 300us, duty cycle \leq 2%

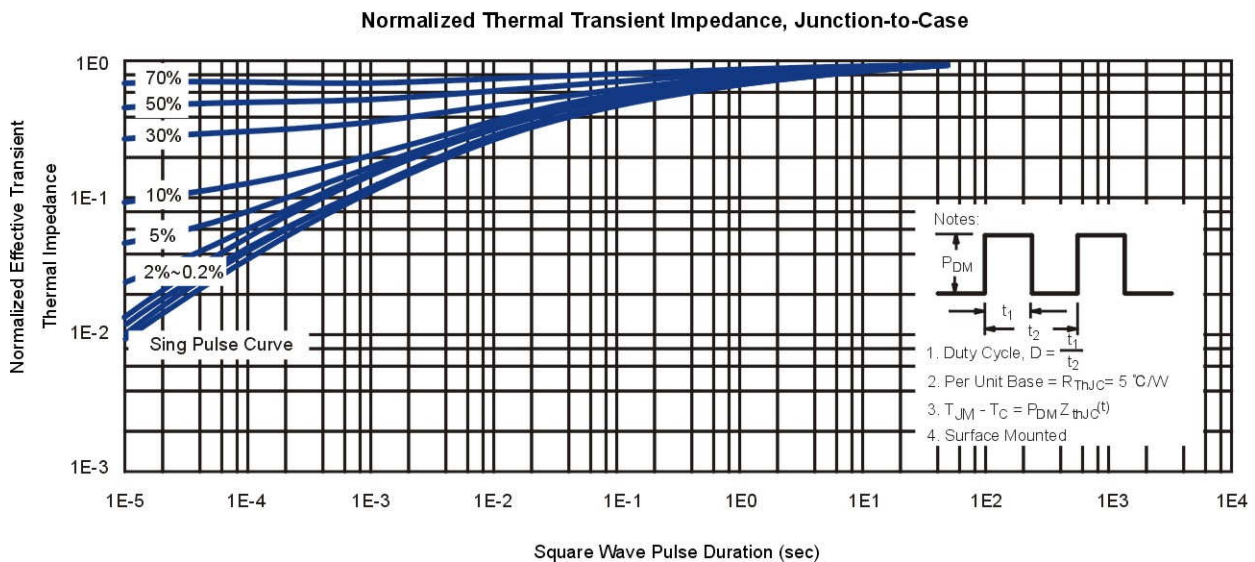
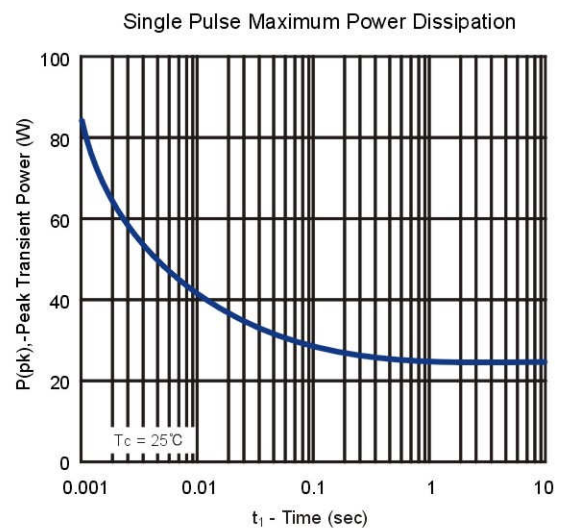
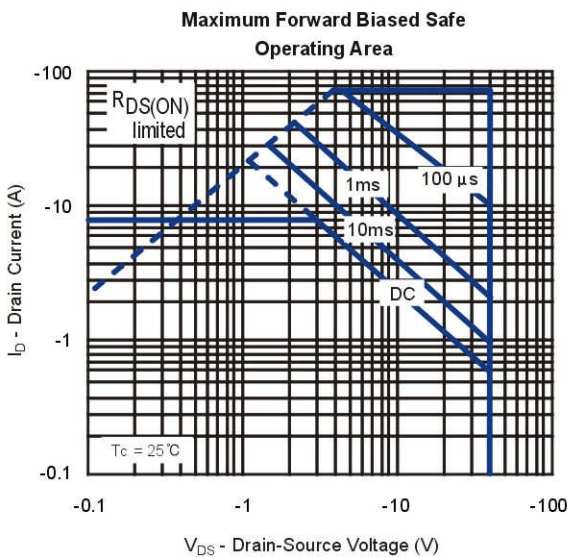
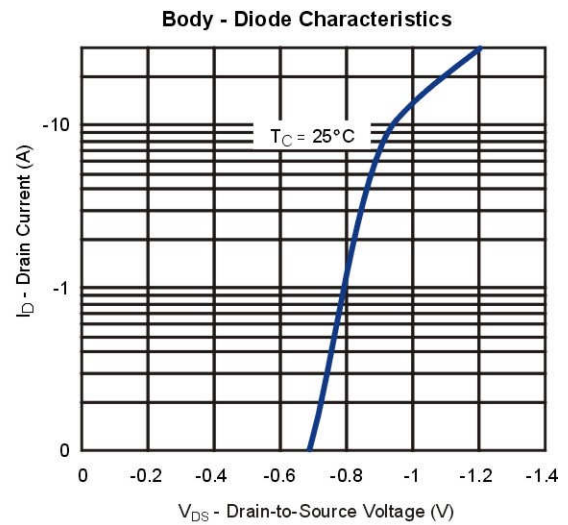
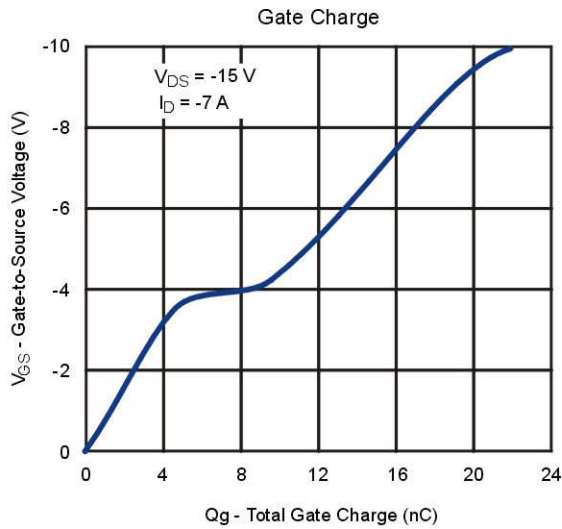
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Typical Characteristics (T_J =25°C Noted)

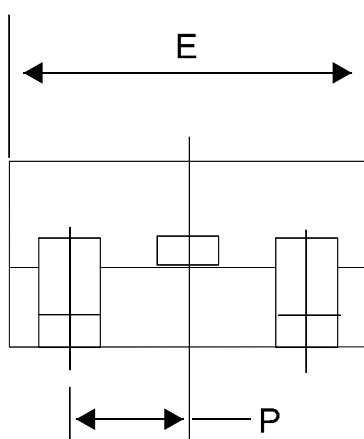
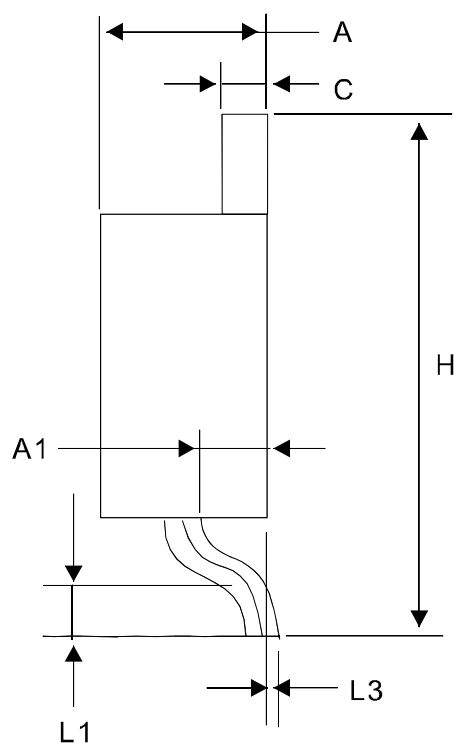
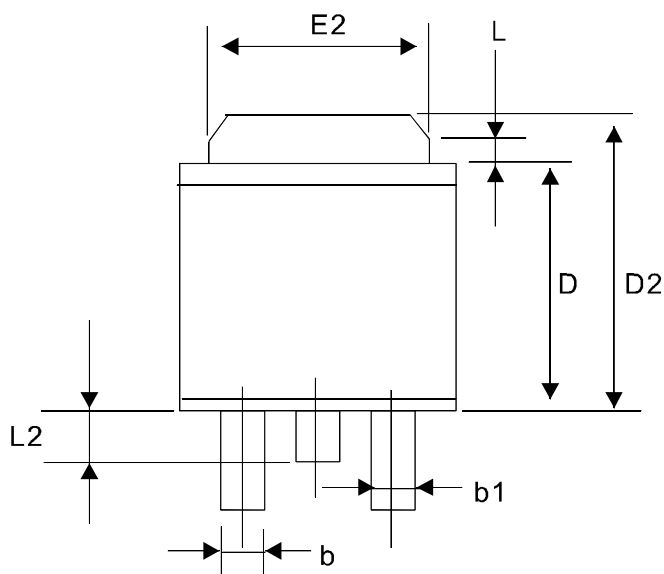


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TO-252 Package Outline



SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.250	2.350	0.089	0.093
A1	0.950	1.050	0.037	0.041
C	0.490	0.530	0.019	0.021
E	6.400	6.600	0.252	0.260
E2	5.300	5.450	0.209	0.215
D	6.000	6.200	0.236	0.244
D2	7.100	7.300	0.280	0.287
H	9.700	10.100	0.382	0.398
L	0.600	Ref	0.024	Ref
L1	1.425	1.625	0.056	0.064
L2	0.650	0.850	0.026	0.033
L3	0.020	0.120	0.001	0.005
b	0.770	0.850	0.030	0.033
b1	0.840	0.940	0.033	0.037
P	2.290	BSC	0.090	BSC